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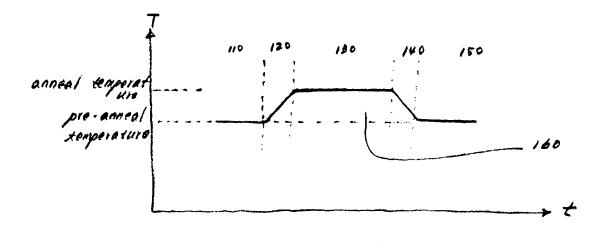


Fig. 1



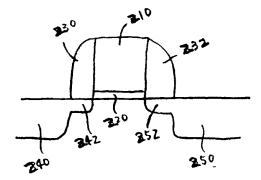


Figure 2

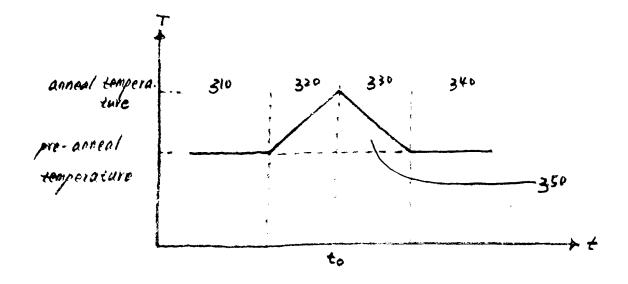
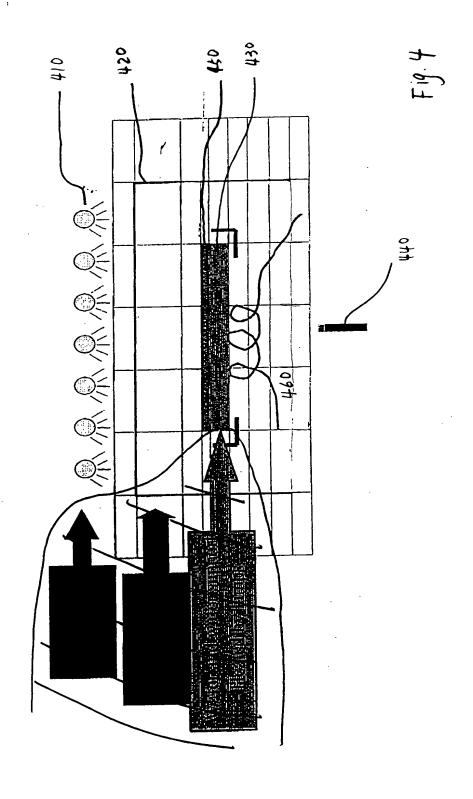


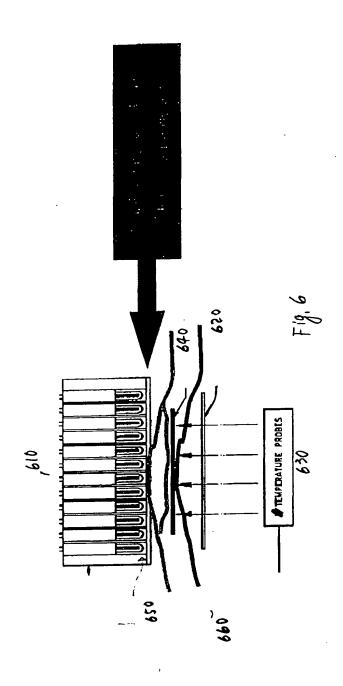
Fig 3

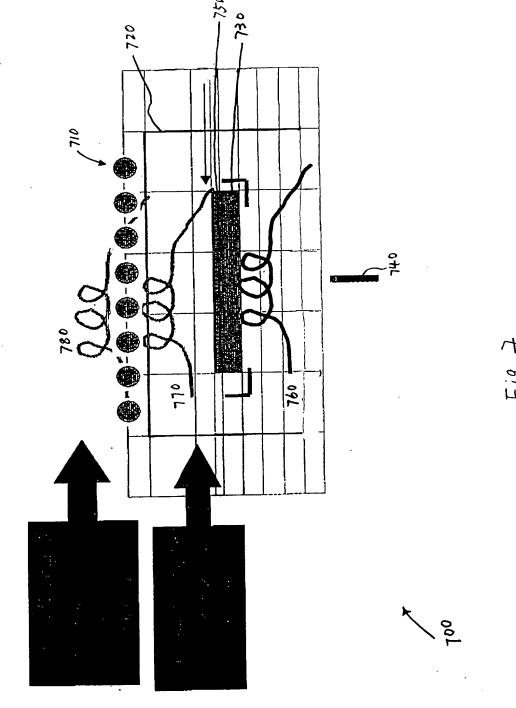
RTP Chamber brief structure





Spike annealing process temperature profile 650,00 600,00 100.00 **T50.00** 1050.00 1000.00 950.00 900.00 850.00 800 00





Mattson RTP system

Turning On At Least 810

One Heat Source Heating a Semiconductor 820 Substrate in a Chamber Turning Off at Least One 830
Heal Source Cooling the Semiconductor 640
Substrate With Gas Flow

Figure 8